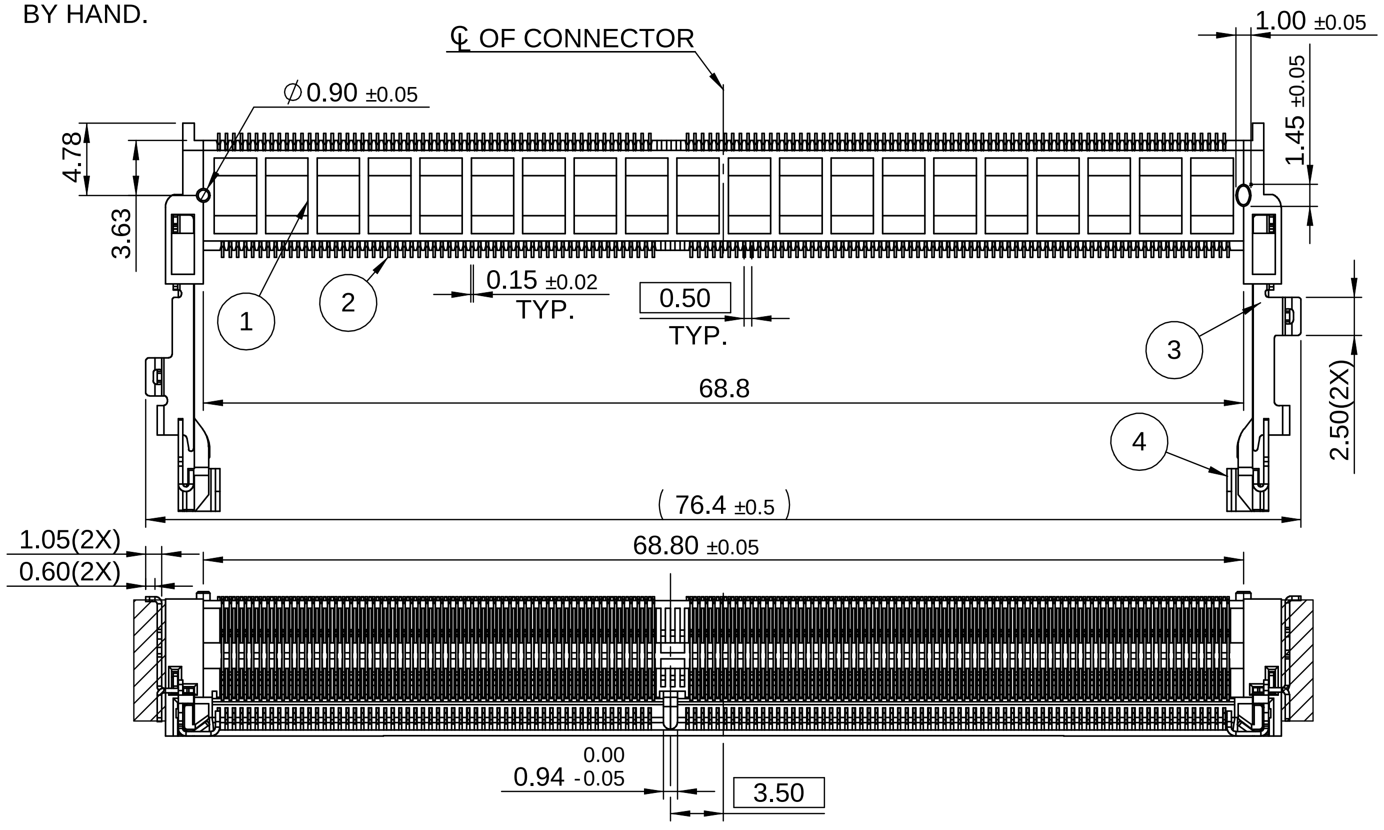
SOLIDWORKS GENERATED DRAWING, DON'T CHANGE
BY HAND.

REV.	ECN. NO.	APPD.
A	BC-15-0029745	C.S Li
B	BC-16-0010201	Bruce Wu
C	BC-16-0024870	Bruce Wu
D	BC-17-0042225	DavyBu



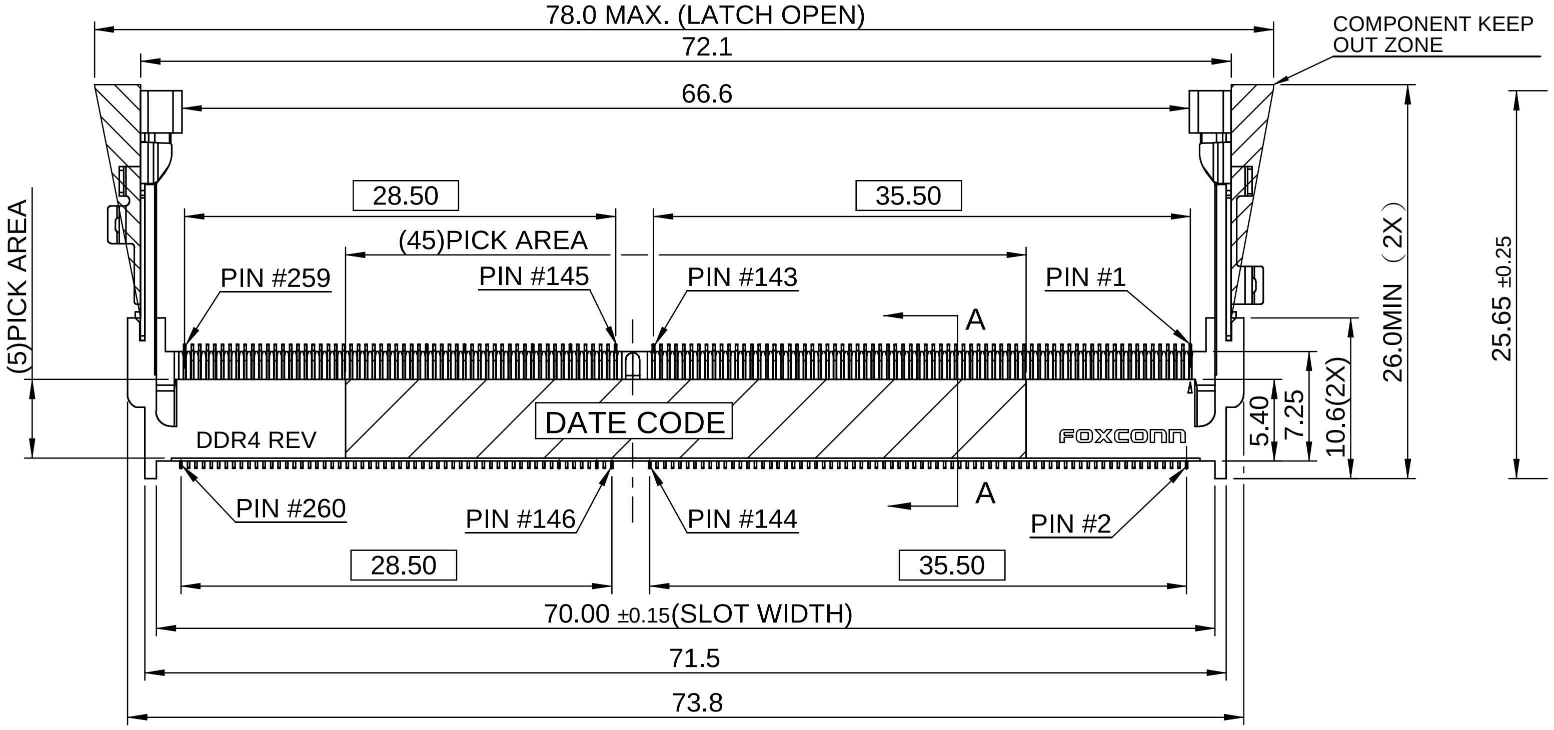
NOTES:
1. ELECTRICAL CHARACTERISTICS:
 1.1. CONTACT CURRENT RATING: 0.5 AMPERE MAX. PER PIN.
 1.2. VOLTAGE RATING: 25V AC.
 1.3. INSULATION RESISTANCE: 100 MEGAOHMS MIN. AT 500V DC.
 1.4. DIELECTRIC WITHSTANDING VOLTAGE: 250V AC RMS AT 60Hz,FOR 1 MINUTE.
 1.5. CONTACT RESISTANCE: 60 MILLIOHMS MAX. PER PIN INITIAL
  △10 MILLIOHMS PER PIN AFTER FULL ENVIRONMENTAL TESTING.
2. MECHANICAL CHARACTERISTICS:DURABILITY: 60 MATING CYCLES.
3. OPERATION TEMPERATURE: -55˚C TO +85˚C.
4. RECOMMENDED PROCESS CONDITION:SMT,PEAK TEMPERATURE:260 ˚C 10~20S.
5. PLEASE CONTACT FOXCONN SALES REPRESENTATIVE TO VERIFY PRODUCT DETAILS
 & AVAILABILITY.

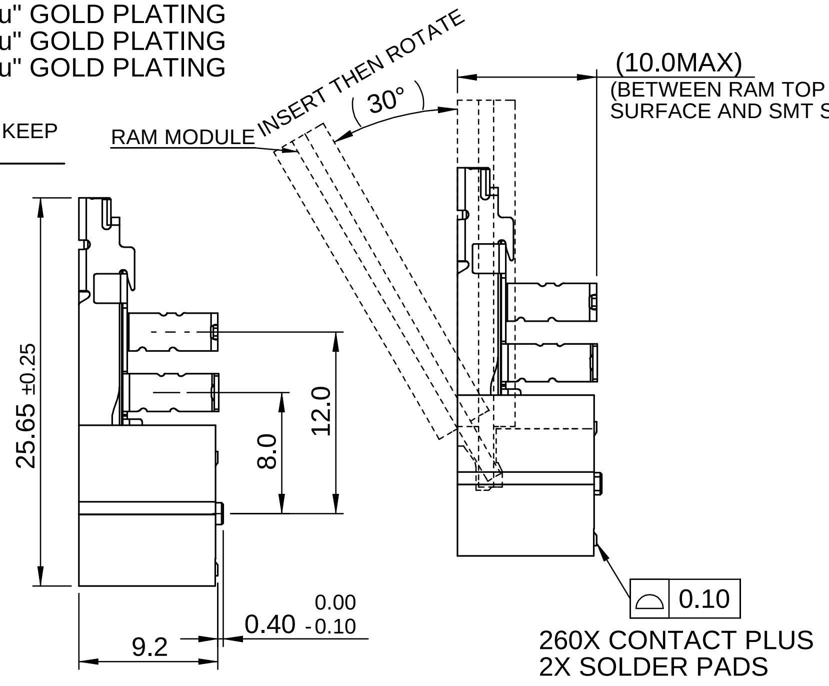
DATE CODE: * * * * *
YEAR
MONTH
DAY
LINE NO.

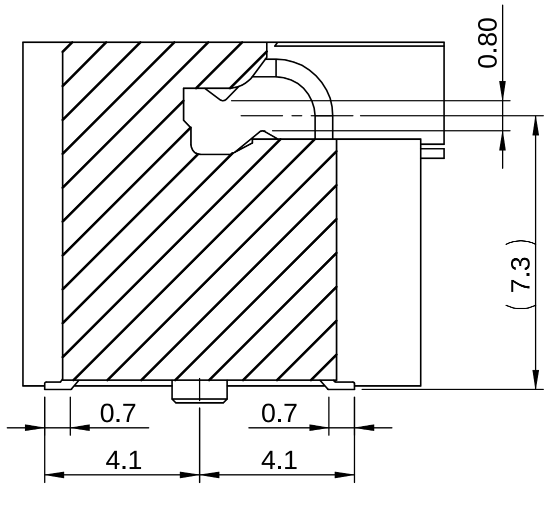
A S A A8 2 * - E A R B 0 - * H

MEMORY MODULE SOCKET
HORIZONTAL TYPE
SINGLE ROW
NO. OF POS.
A8=260 POS.
SMT
CONTACT AREA PLATING
1=GOLD FLASH
Y=5u" GOLD PLATING
6=10u" GOLD PLATING
7=15u" GOLD PLATING
3=30u" GOLD PLATING

H=HALOGEN FREE & LEAD FREE
7=TAPE REEL
4=SOFT TRAY
0=EXTENSION CODE
B=NORMAL TYPE,BLACK COLOR
R=REVERSE
A=9.2MM HEIGHT
E=DDR SODIMM







SECTION A-A

ITEM	DESCRIPTION	Q'TY	METERIAL	TREATMENT
4	METAL SPRING	2	STAINLESS STEEL SUS 301	ULTRASONIC CLEANING
3	METAL PAD	2		10u" NICKEL UNDER PLATING 100u" MATTE TIN PLATING OVER SOLDER PAD AREA.
2	CONTACT	260	PHOSPHOR BRONZE C5210	50u" NICKEL UNDER PLATING GOLD FLASH OR 5u" OR 10u" AT CONTACT AREA; 90u" NICKEL UNDER PLATING 15u" OR 30u" GOLD PLATING AT CONTACT AREA; GOLD FLASH PLATING AT TAIL
1	HOUSING	1	LCP SV6808THF	UL94V-0, HALOGEN FREE, BLACK COLOR

X. ± 0.30	X.° ±
.X ± 0.25	.X° ±
.XX ± 0.15	.XX° ±
.XXX ±	.XXX° ±

UNITS mm
MAT'L
FINISH
Q'TY

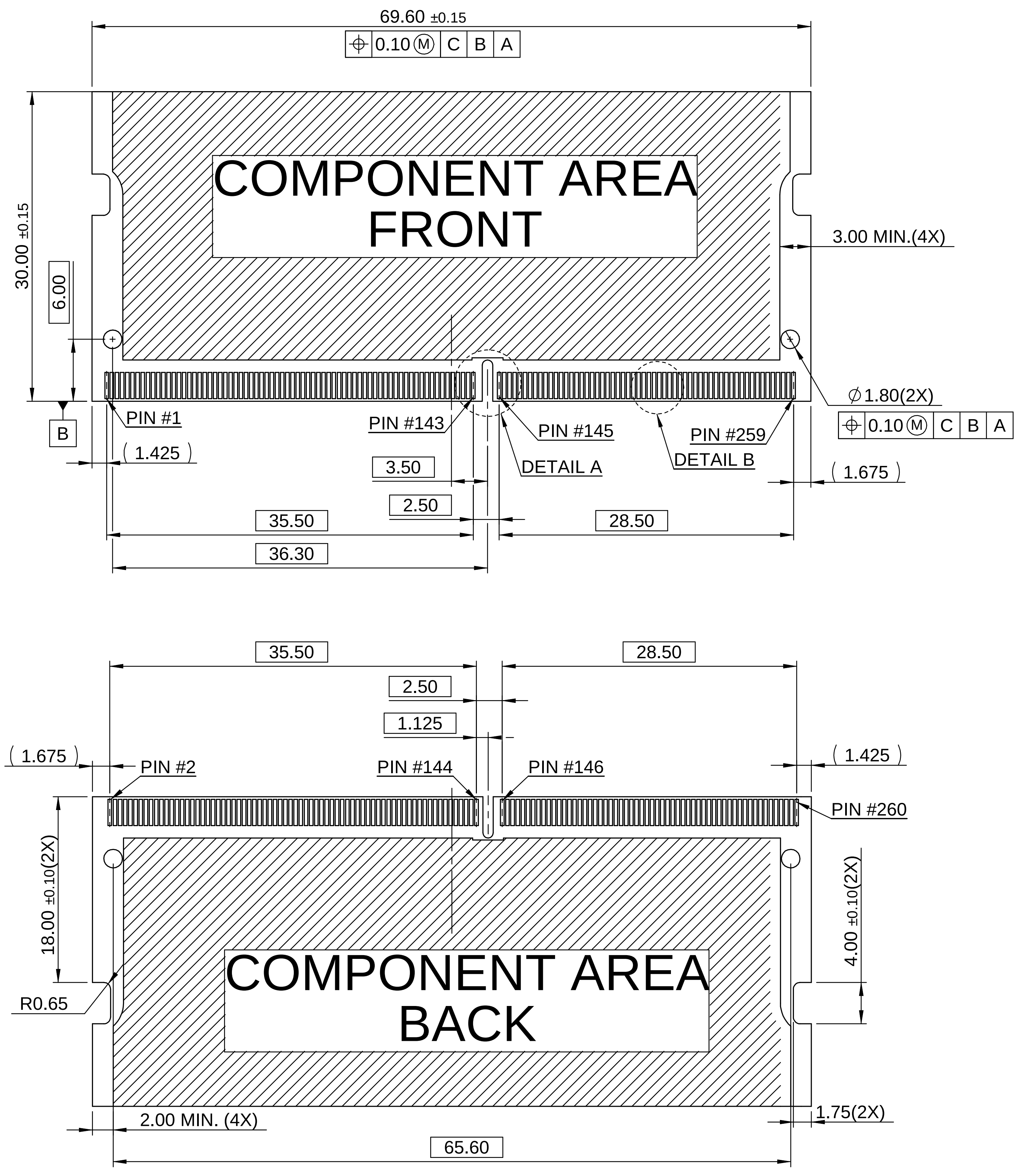
NAME(INTENDED USE)
DDR4 SO DIMM CONN.
PART NO.(INTENDED USE)
ASAA82*-EARB0-*H
APPD: Davy Bu
CHKD: Z.J.Chen
DRAW: Sanford Jiang 2017/12/15

FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
CLASS:
☐CONFIDENTIAL ☐ SECRET ■GENERAL
TITLE: CUSTOMER DRAWING
260PIN SODDR4 9.2 REV.
DWG NO.: 317-0000-2534

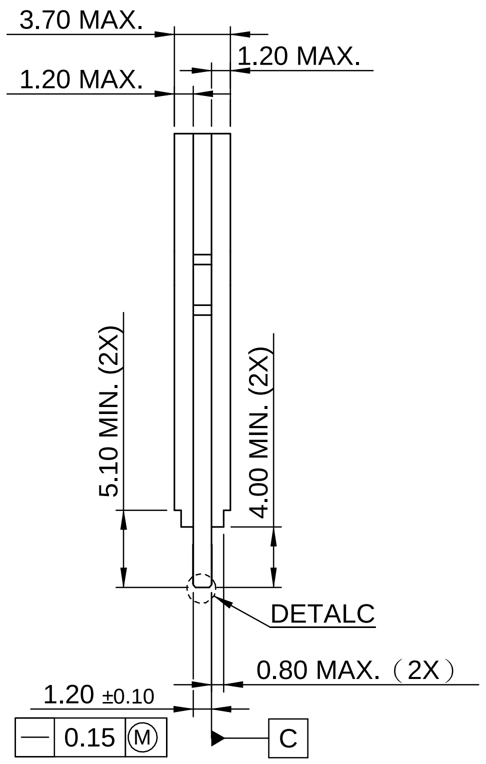
SCALE	SHEET	REV.
N/A	1/6	D

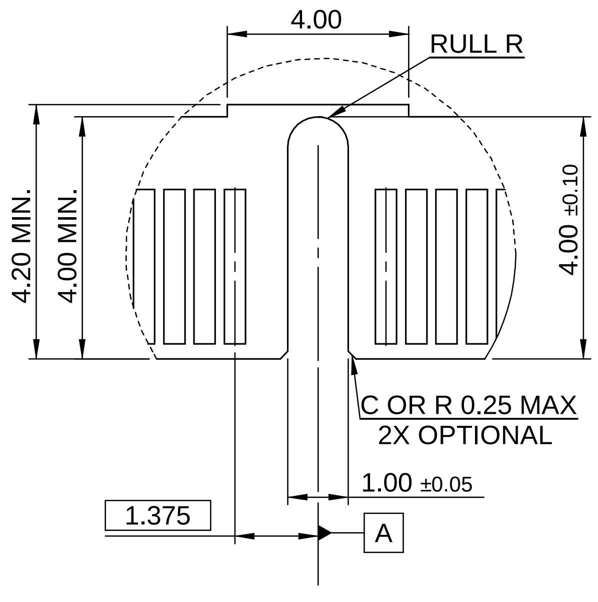
SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.

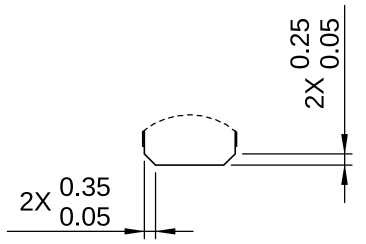


DDR4 SO DIMM MODULE BOARD LAYOUT

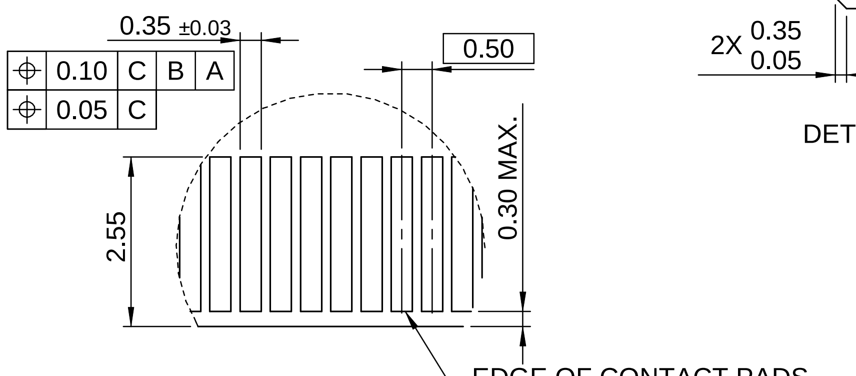




DETAIL A



DETAIL C



DETAIL B

EDGE OF CONTACT PADS SHALL BE FREE OF BURRS

X.± 0.25	X.° ±	UNITS mm	NAME(INTENDED USE) DDR4 SO DIMM CONN.
.X± 0.10	.X° ±	MAT'L	PART NO.(INTENDED USE) ASAA82*-EARB0-*H
.XX± 0.05	.XX° ±		
.XXX±	.XXX° ±	FINISH	APPD: Davy Bu
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			DRAW: Sanford Jiang 2017/12/15

FIT
FOXCONN INTERCONNECT TECHNOLOGY LIMITED.

CLASS:
☐CONFIDENTIAL ☐ SECRET ■GENERAL

TITLE: CUSTOMER DRAWING
260PIN SODDR4 9.2 REV.

DWG NO.: 317-0000-2534

SCALE	SHEET	REV.
N/A	2/6	D

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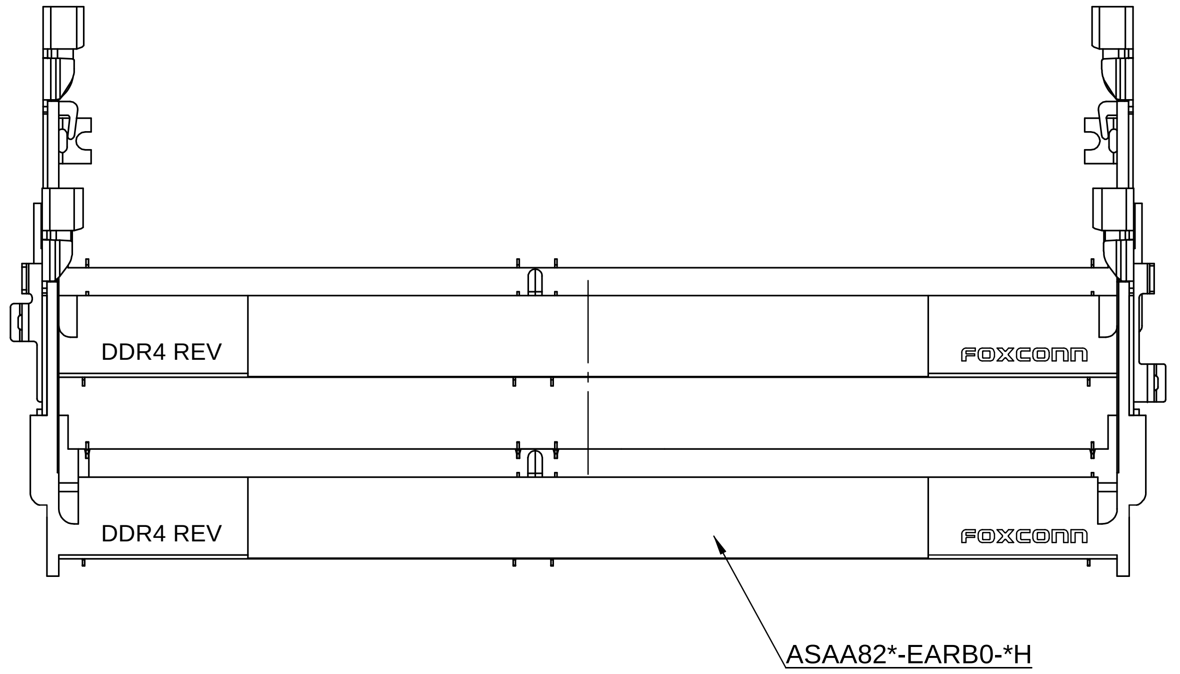
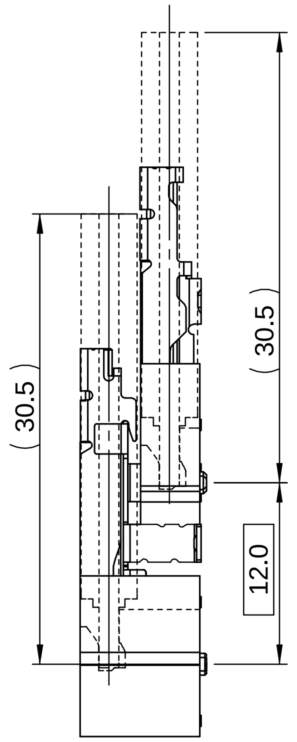
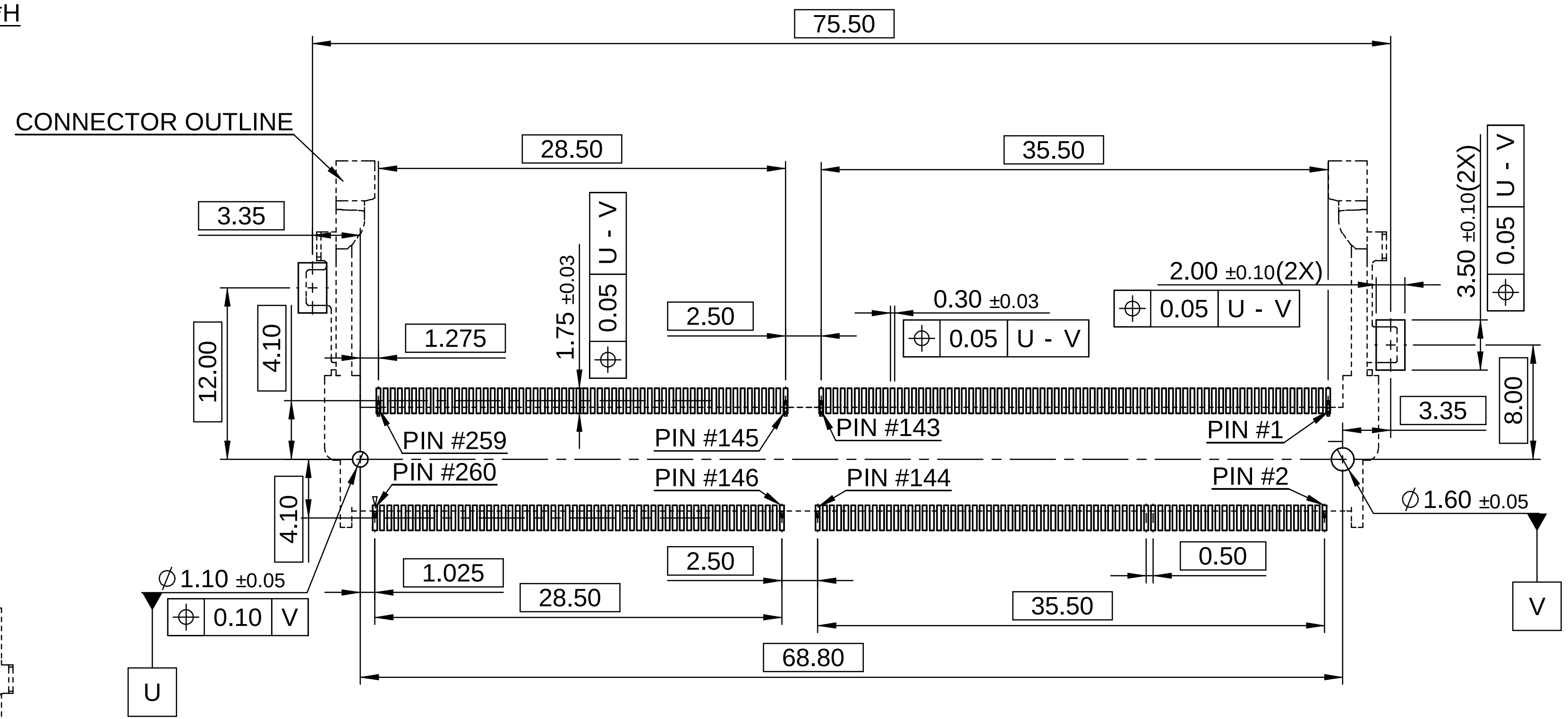
BY HAND.

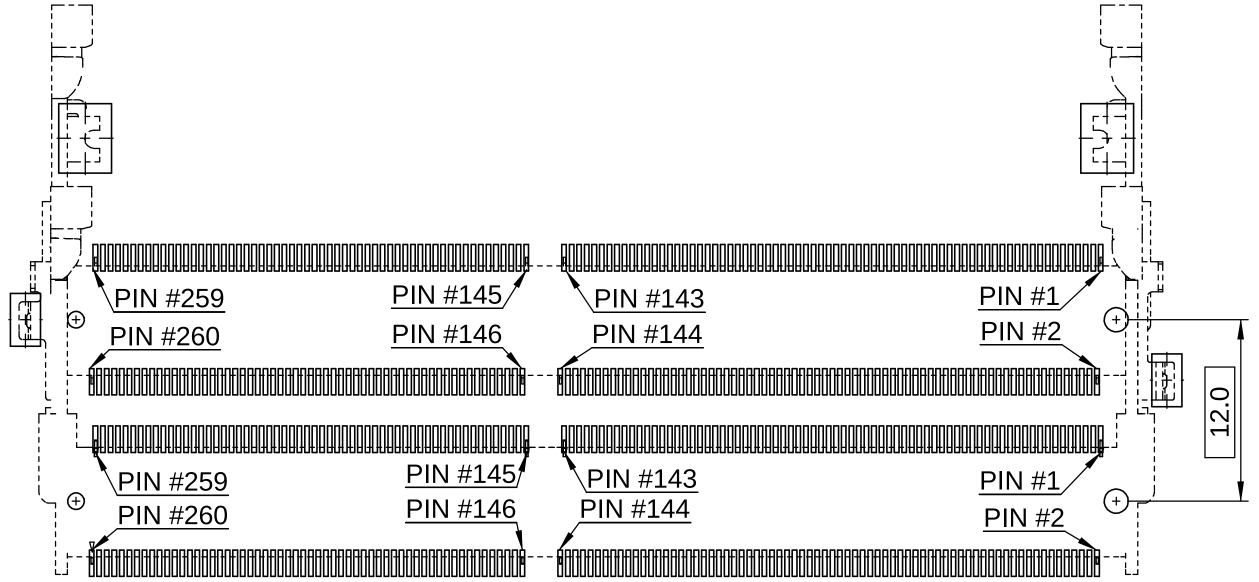
REV.	ECN. NO.	APPD.







P.C.B. LAYOUT(RECOMMEND THICKNESS =1.40MM)



X. ±	0.25	X.° ±
.X ±	0.10	.X° ±
.XX ±	0.05	.XX° ±
.XXX ±		.XXX° ±

UNITS mm
MAT'L
FINISH
Q'TY

NAME(INTENDED USE)
DDR4 SO DIMM CONN.

PART NO.(INTENDED USE)
ASAA82*-EARB0-*H

APPD: Davy Bu
CHKD: Z.J.Chen
DRAW: Sanford Jiang 2017/12/15

FIT™ FOXCONN INTERCONNECT TECHNOLOGY LIMITED.

CLASS:
☐CONFIDENTIAL ☐SECRET ■GENERAL

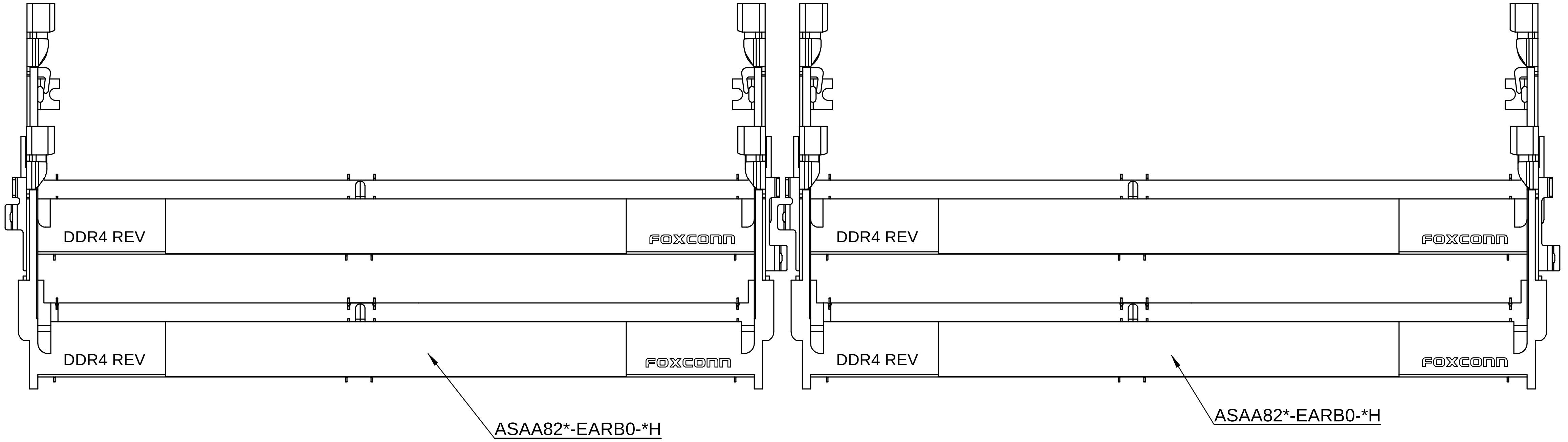
TITLE: CUSTOMER DRAWING
260PIN SODDR4 9.2 REV.

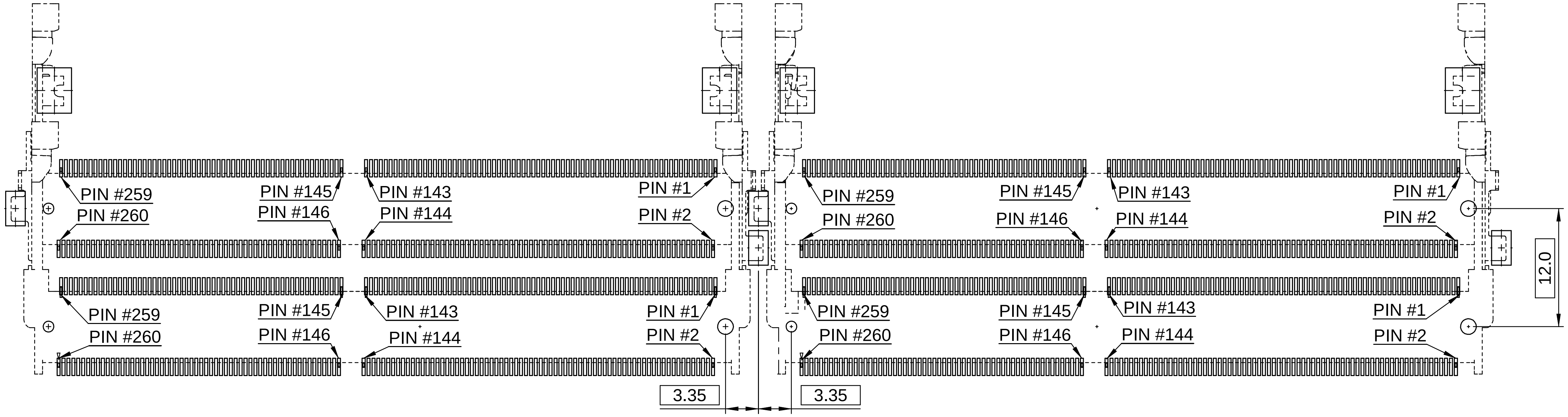
DWG NO.:
317-0000-2534

SCALE	SHEET	REV.
N/A	3/6	D

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

REV.	ECN. NO.	APPD.





P.C.B. LAYOUT(DUAL COMPRESSED STACKED ORIENTATION)

X. ± 0.25	X.° ±	UNITS mm	NAME(INTENDED USE) DDR4 SO DIMM CONN.	FOXCONN INTERCONNECT TECHNOLOGY LIMITED.
.X ± 0.10	.X° ±	MAT'L	PART NO.(INTENDED USE) ASAA82*-EARB0-*H	CLASS: ☐CONFIDENTIAL ☐SECRET ■GENERAL
.XX ± 0.05	.XX° ±			TITLE: CUSTOMER DRAWING 260PIN SODDR4 9.2 REV.
.XXX±	.XXX° ±	FINISH	APPD: Davy Bu	DWG NO.: 317-0000-2534
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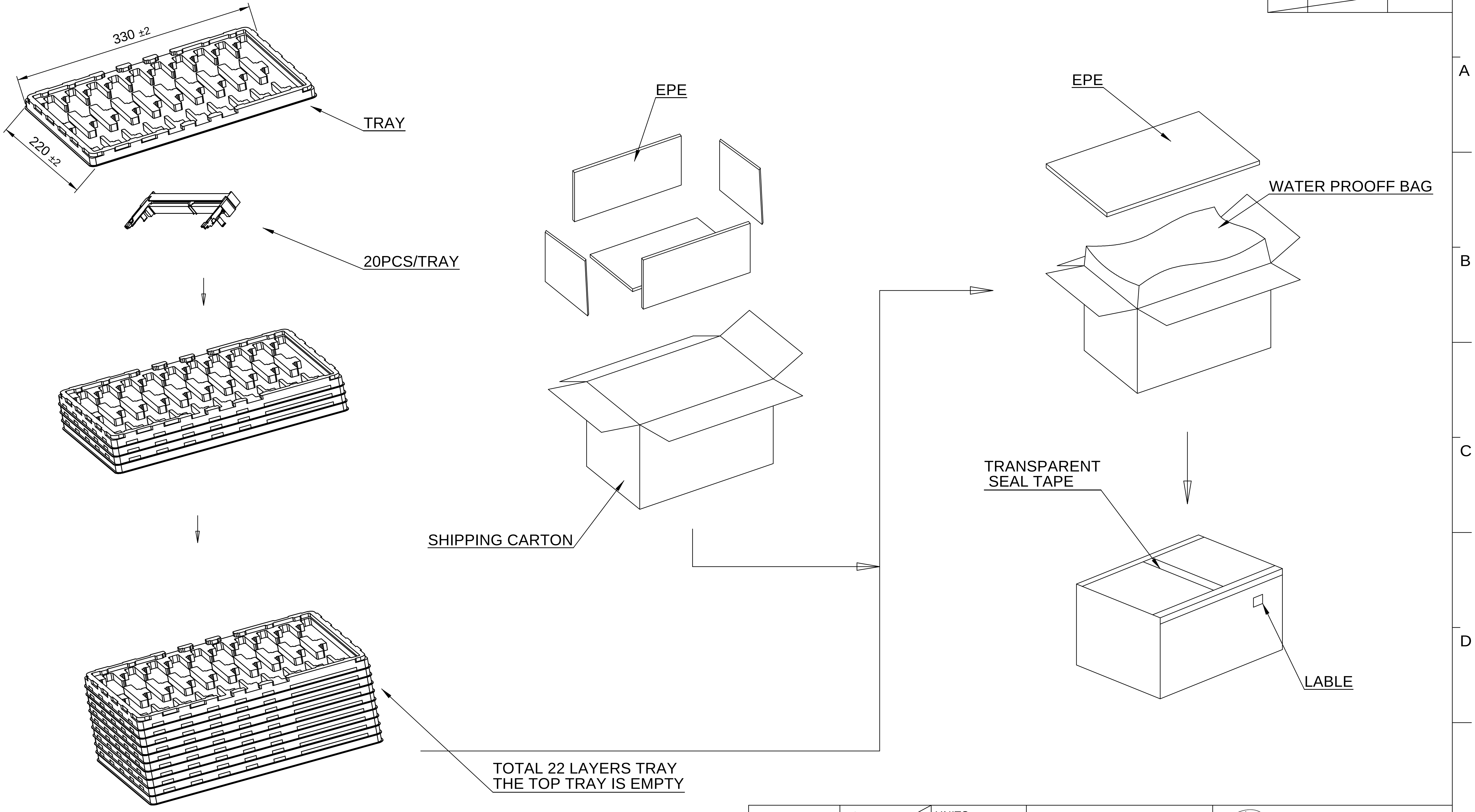
			DRAW: Sanford Jiang 2017/12/15	

SOLIDWORKS GENERATED DRAWING, DON'T CHANGE
BY HAND.

REV.	ECN. NO.	APPD.



PACKING CAPACITY : 20 PCS/TRAY, 21 TRAYS/BOX,
TOTAL 420 PCS/BOX.

CONNECTOR P/N	ASAA82*-EARB0-4H

X. ± 1.5	X.° ±	UNITS mm	NAME(INTENDED USE) DDR4 SO DIMM CONN.
.X ± 1.0	.X° ±	MAT'L	PART NO.(INTENDED USE) ASAA82*-EARB0-*H
.XX ± 0.2	.XX° ±	FINISH	APPD: Davy Bu
.XXX ±	.XXX° ±	Q'TY	CHKD: Z.J.Chen
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FOXCONN INTERCONNECT
TECHNOLOGY LIMITED.

CLASS:
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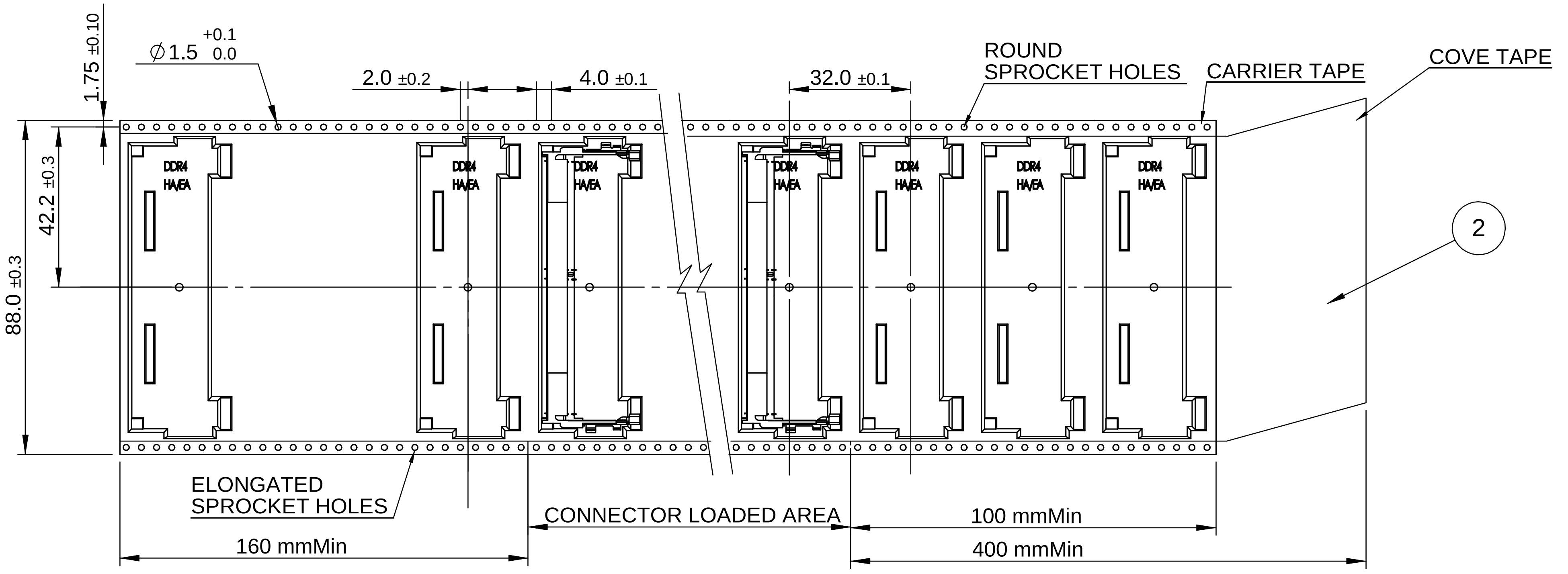
TITLE: CUSTOMER DRAWING
260PIN SODDR4 9.2 REV.

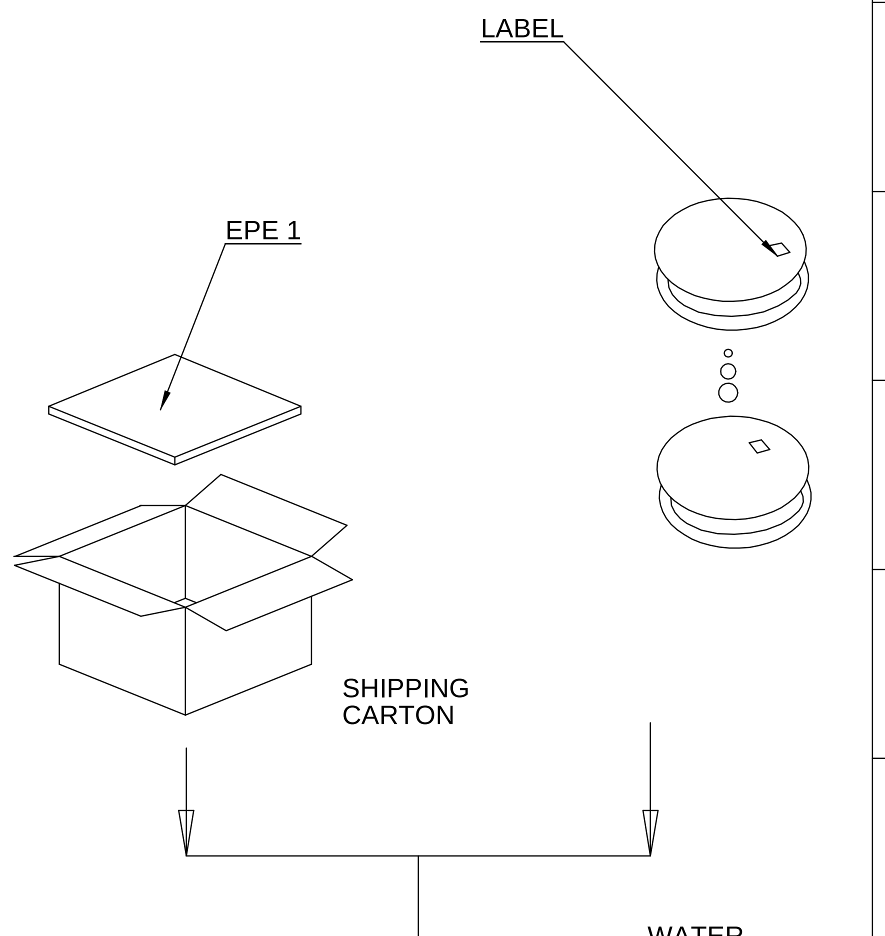
DWG NO.: 317-0000-2534

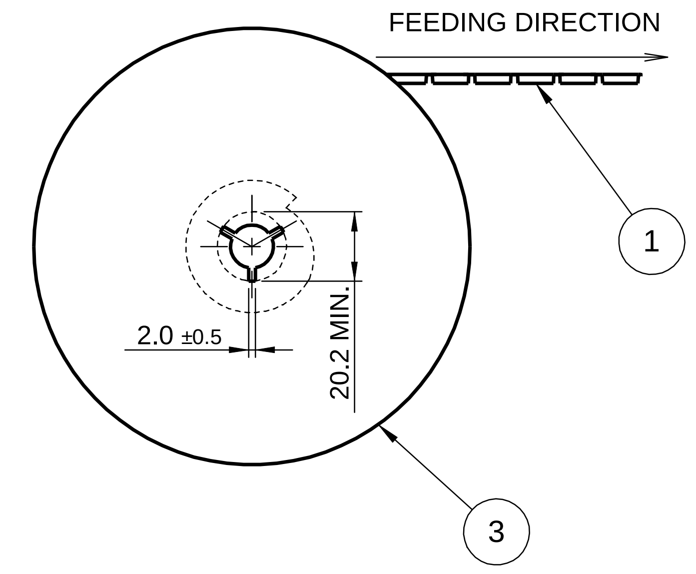
SCALE	SHEET	REV.
N/A	5/6	D

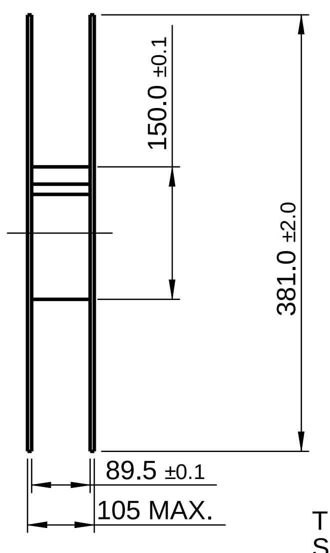
SOLIDWORKS GENERATED DRAWING, DON'T CHANGE BY HAND.

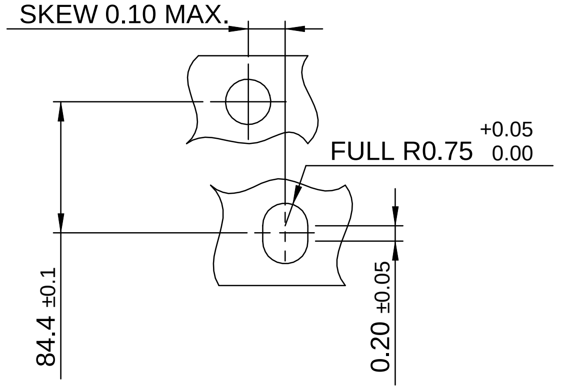
REV.	ECN. NO.	APPD.



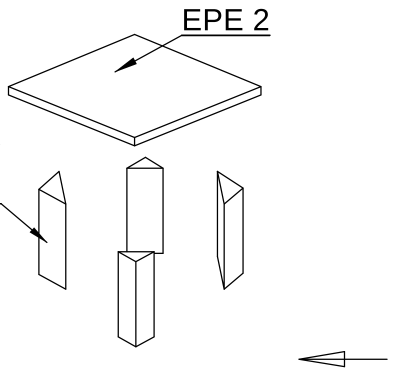


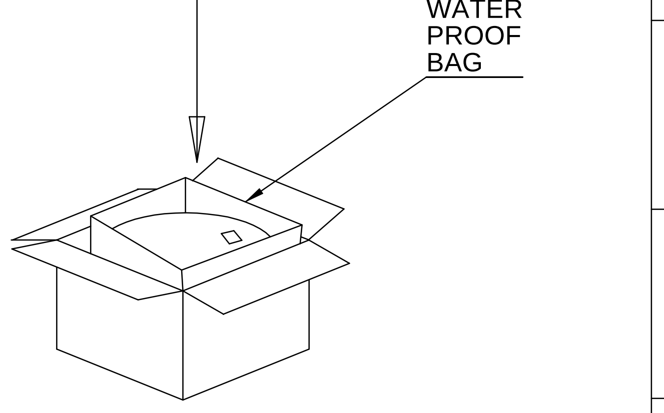


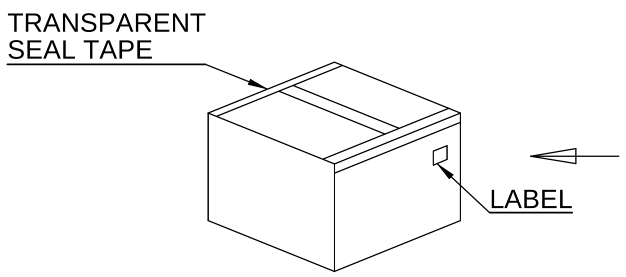




DETAIL:
ELONGATION AND SKEW OF SPROCKET HOLES

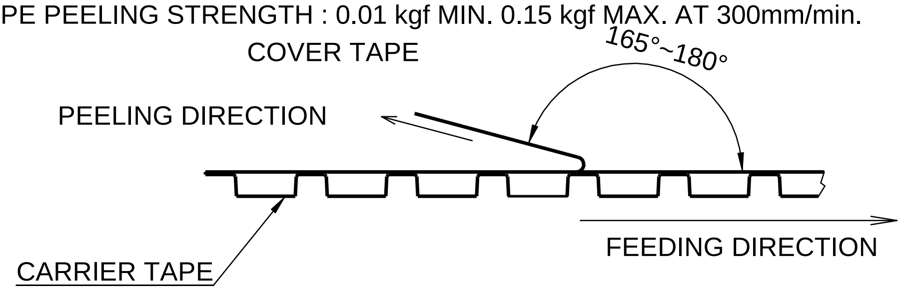






NOTES:

1. 10 POCKETS HOLE PITCH CUMULATIVE TOLERANCE ±0.20mm.
2. COVER TAPE PEELING STRENGTH : 0.01 kgf MIN. 0.15 kgf MAX. AT 300mm/min.



3. PACKING CAPACITY : 230 PCS/REEL, 3 REELS/BOX, TOTAL 690 PCS/BOX.

ITEM	DESCRIPTION	MATERIAL
3	REEL	POLYSTYRENE
2	COVER TAPE	POLYESTER
1	CARRIER TAPE	POLYSTYRENE

X. ±	1.5	X.° ±	
.X ±	1.0	.X° ±	
.XX ±	0.2	.XX° ±	
.XXX ±		.XXX° ±	

UNITS mm
MAT'L
FINISH
Q'TY

NAME(INTENDED USE)
DDR4 SO DIMM CONN.

PART NO.(INTENDED USE)
ASAA82*-EARB0-*H

APPD: Davy Bu
CHKD: Z.J.Chen
DRAW: Sanford Jiang 2017/12/15

FOXCONN INTERCONNECT TECHNOLOGY LIMITED.

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TITLE: CUSTOMER DRAWING
260PIN SODDR4 9.2 REV.

DWG NO.:
317-0000-2534

SCALE	SHEET	REV.
N/A	6/6	D

CONNECTOR P/N	ASAA82*-EARB0-7H

FK2B00065D